



Material Content Data Sheet



Sales Product Name	ESD102-U2-099EL E6327				Issued		29. August 2013	
MA#	MA001091362							
Package	PG-TSLP-4-10				Weight*		0.42 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.16		1650	
	noble metal	gold	7440-57-5	0.003	0.64		6403	
	inorganic material	silicon	7440-21-3	0.020	4.74	5.54	47445	55498
leadframe	non noble metal	nickel	7440-02-0	0.066	15.74	15.74	157375	157375
wire	non noble metal	copper	7440-50-8	0.004	0.86	0.86	8609	8609
encapsulation	organic material	carbon black	1333-86-4	0.002	0.36		3638	
	plastics	epoxy resin	-	0.045	10.55		105516	
	inorganic material	silicondioxide	60676-86-0	0.261	61.87	72.78	618544	727698
leadfinish	noble metal	gold	7440-57-5	0.010	2.29	2.29	22902	22902
plating	noble metal	palladium	7440-05-3	0.003	0.66		6623	
	noble metal	gold	7440-57-5	0.009	2.13	2.79	21295	27918
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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